

GXO-3300 - 3225 High Precision Oscillator


Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Base	Ceramic	Al ₂ O ₃	1344-28-1	13.990	64.38
	Ceramic	SiO ₂	14808-60-7	0.680	3.13
	Ceramic	CaO	1305-78-8	0.100	0.46
	Ceramic	MgO	1309-48-4	0.090	0.41
	Ceramic	Cr ₂ O ₃ (Non hex)	1308-38-9	0.110	0.51
	Ceramic	Mo	7439-98-7	0.140	0.64
	Metal Layer	W	7440-33-7	2.950	13.58
	Metal Layer	Mo	7439-98-7	0.090	0.41
	Plated Au	Au	7440-57-5	0.130	0.60
	Plated Au	Tl	7440-28-0	0.000	0.00
	Plated Ni	Ni	7440-02-0	0.380	1.75
	Plated Ni	Co	7440-48-4	0.090	0.41
	Seal Ring	Fe	7439-89-6	1.210	5.57
	Seal Ring	Ni	7440-02-0	0.650	2.99
	Seal Ring	Co	7440-48-4	0.380	1.75
	Silver Solder	Ag	7440-22-4	0.630	2.90
	Silver Solder	Cu	7440-50-8	0.110	0.51
	Cap	Kovar	Fe	7439-89-6	1.526
Kovar		Ni	7440-02-0	0.835	27.49
Kovar		Co	7440-48-4	0.459	15.11
Kovar		Mn	7439-96-5	0.007	0.23
Kovar		Si	7440-21-3	0.001	0.03
Kovar		C	7440-44-0	0.000	0.00
Plated Ni		Ni	7440-02-0	0.210	6.91
Crystal	Adhesive	Ag	7440-22-4	0.370	37.34
	Adhesive	Silicon Resin	7631-86-9	0.062	6.26
	Adhesive	SiO ₂ (Fibre Glass)	7631-86-9	0.063	6.36
	Crystal	SiO ₂	14808-60-7	0.484	48.84
	Electode	Co	7440-48-4	0.012	1.21
	Electode	Ni	7440-02-0	0.000	0.00
IC	Adhesive	Ag	7440-22-4	0.188	25.13
	Adhesive	Epoxy	129915-35-1	0.063	8.42
	IC	Si	7440-21-3	0.209	27.94
	IC	Al	7429-90-5	0.001	0.13
	IC	P	7723-14-0	0.000	0.00
	IC	B	7440-42-8	0.000	0.00
	IC	As	7440-38-2	0.000	0.00
	IC	Ti	7440-32-6	0.000	0.00
	IC	W	7440-33-7	0.000	0.00
	IC	Cu	7440-50-8	0.000	0.00
	Wire	Au	7440-57-5	0.287	38.37

Material Composition Data

Product: GXO-3300

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Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
				Total Mass:	26.507 mg
		 <hr/>	John Hems Quality Manager Email: j.hems@golledge.com		